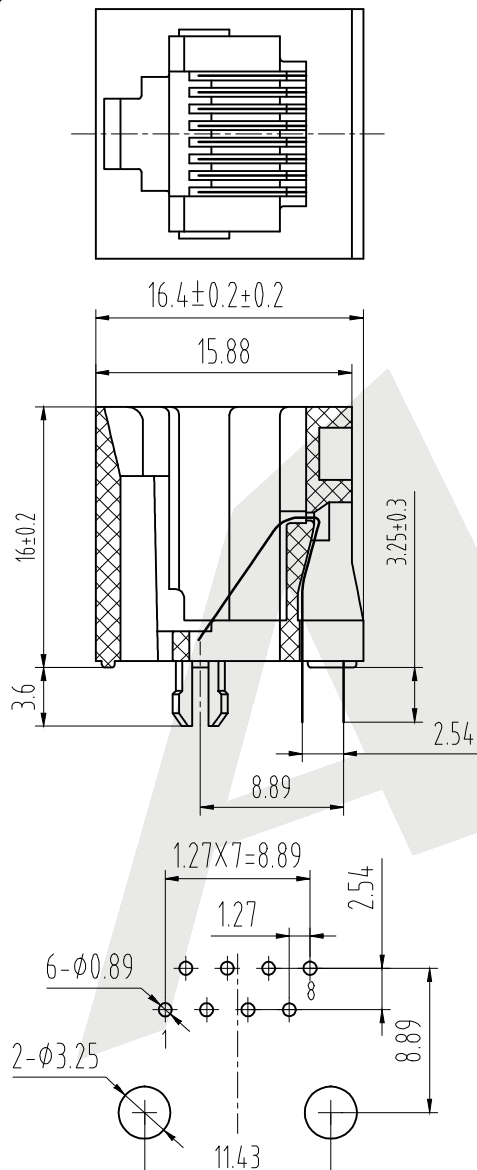
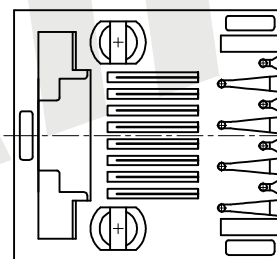
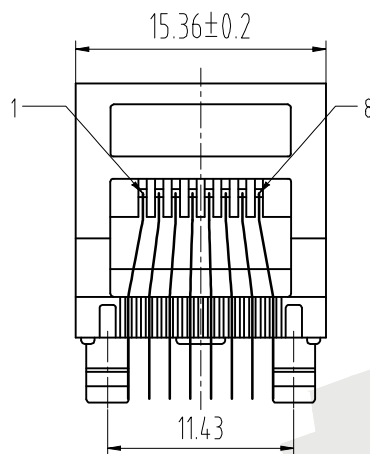


HSF



PC Board Layout
Component Side Shown



NOTES:

MATERIAL:

- HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
 - CONTACT MATERIAL: PHOSPHOR BRONZE $t=0.3\text{mm}$
 - PLATING: SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATIN. OVER NICKEL IN SOLDER AREA
 - SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE
- ELECTRICAL
- VOLTAGE RATING: 125VAC RMS
 - CURRENT RATING: 1.5AMP
 - CONTACT RESISTANCE: 30 MILLIOHMS MAX
 - INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
 - DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

- DURRABILITY: 750 CYCLES MIN
- PCB RETENTTON PRB-SOLDER: 1 LB MIN

REVISIONAL

- STORAGE: -40°C TO 85°C
- OPERATION: 0°C TO 70°C

Order code:

ATRJ5221 -8P - 8C - X - A - X

① ② ③ ④ ⑤ ⑥

- | | |
|------------------------------------|-------------------|
| ① SERIES NO: | ⑤ Shield |
| ② NUMBER OF POSITIONS (8P, 6P, 4P) | A: W/O Shield |
| ③ NUMBER OF CONTACTS (8C, 6C, 4C) | B: Half Shield |
| ④ Contact Plating | C: Shield W/Eml |
| G0: Gold flash | D: Shield W/O Eml |
| G1: 3U" Gold | ⑥ Ports |
| G2: 5U" Gold | A: 1X1P |
| G3: 10U" Gold | B: 1X2P |
| G4: 15U" Gold | C: 1X4P |
| G5: 30U" Gold | D: 1X5P |
| SN: Tin | E: 1X6P |
| | F: 1X8P |

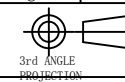
Unless Otherwise specified tolerance
X. ± 0.35 X.XX: ± 0.20
X.X: ± 0.25 X.XXX: ± 0.15

Antenk ANTENK ELECTRONICS CO., LTD
[Http://www.antenk.com](http://www.antenk.com)
E-mail: sales@antenk.com

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 25/07/2019
CHECK BobYang	DATE 25/07/2019

TITLE: RJ45 Jack Top entry 8P8C
Full Plastic

DRAWING NO: ATRJ5221-8P8C-X-A-X-B
PRODUCT NO: ATRJ5221-8P8C-X-A-X-B



REV	DESCRIPTION	DATE
1		
2		
3		
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